

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1-26. (Canceled)

27. (Withdrawn) A method for removing at least one material selected from metals, metal oxides or polymer dielectrics from a substrate comprising:

(a) applying to said substrate a slurry which comprises silica having an aggregate of primary particles, said primary particles having an average diameter of at least seven (7) nanometers, wherein said aggregate has an aggregate size of less than one (1) micron, and a hydroxyl content of at least seven (7) hydroxyl groups per nanometer squared, and a liquid;

(b) placing a polishing pad at least partially in contact with said substrate; and

(c) rotating said polishing pad.

28. (Withdrawn) The method of claim 27 wherein said material is selected from copper, tantalum, tungsten and aluminum.

29. (Withdrawn) The method of claim 27 wherein said material is silicon dioxide.

30. (Withdrawn) The method of claim 28 wherein said material is copper and tantalum.

31. (Withdrawn) The method of claim 30 wherein removal of tantalum is at a rate equal to or greater than removal rate of copper.

32-35. (Canceled)

36. (Original) A slurry for chemical mechanical planarization of a substrate comprising silica having an aggregate of primary particles, said aggregate having an aggregate size of less than one (1) micron, and said silica having an DHP oil absorption value of at least 150 milliliters per 100 grams of silica.

37-45. (Canceled)

46. (New) A silica comprising:

(a) an aggregate of primary particles, said primary particles having an average diameter of at least fifteen (15)

nanometers, wherein said aggregate has an aggregate size of less than one (1) micron; and

(b) a hydroxyl content of at least seven (7) hydroxyl groups per nanometer squared.

47. (New) A silica comprising:

(a) an aggregate of primary particles, said primary particles having an average diameter of at least seven (7) nanometers, wherein said aggregate has an aggregate size of less than one (1) micron; and

(b) a hydroxyl content of at least ten (10) hydroxyl groups per nanometer squared.

48. (New) The silica of claim 47 wherein said hydroxyl content is at least fifteen (15) hydroxyl groups per nanometer squared.

49. (New) A slurry composition comprising:

(a) silica having an aggregate of primary particles, said primary particles having an average diameter of at least fifteen (15) nanometers, said aggregate having an aggregate size of less than one (1) micron, and said silica having a hydroxyl content of at least seven (7) hydroxyl groups per nanometer squared; and

(b) a liquid.

50. (New) A slurry composition comprising:

(a) silica having an aggregate of primary particles, said primary particles having an average diameter of at least seven (7) nanometers, said aggregate having an aggregate size of less than one (1) micron, and said silica having a hydroxyl content of at least ten (10) hydroxyl groups per nanometer squared; and

(b) a liquid.

51. (New) The slurry composition of claim 50 wherein said hydroxyl content is at least fifteen (15) hydroxyl groups per nanometer squared.

52. (New) A slurry composition comprising:

(a) silica having an aggregate of primary particles, said primary particles having an average diameter of at least seven (7) nanometers, said aggregate having an aggregate size of less than one (1) micron, and said silica having a hydroxyl content of at least seven (7) hydroxyl groups per nanometer squared;

(b) a liquid; and

(c) oxidizing agent selected from inorganic and organic per-compounds, bromic acid, chloric acid, nitrates, sulfates, or mixtures thereof.

53. (New) The slurry composition of claim 52 wherein said oxidizing agent is selected from urea-hydrogen peroxide, hydrogen peroxide, or a mixture thereof.

54. (New) A slurry composition comprising:

(a) silica having an aggregate of primary particles, said primary particles having an average diameter of at least seven (7) nanometers, said aggregate having an aggregate size of less than one (1) micron, and said silica having a hydroxyl content of at least seven (7) hydroxyl groups per nanometer squared;

(b) a liquid;

(c) polyvalent cation sequestrant; and

(d) corrosion inhibitor.

55. (New) The slurry composition of claim 54 wherein said polyvalent cation sequestrant is selected from carboxylic acids, polycarboxylic acids, amino acids, polyamino acids, dipeptides, polyimines, phosphoric acids, polyphosphoric acids, or mixtures thereof.

56. (New) The slurry composition of claim 54 wherein said polyvalent cation sequestrant is selected from glycine, histidine, phytic acid, or mixtures thereof.

57. (New) The slurry composition of claim 54 wherein said corrosion inhibitor is selected from polycarboxylic acids, polyamino acids, amino acids, imines, azoles, carboxylated azoles, mercaptans, or mixtures thereof.

58. (New) The slurry composition of claim 54 wherein said corrosion inhibitor is selected from histidine, phytic acid or a mixture thereof.

59. (New) The slurry composition of claim 54 further comprising a thickener.

60. (New) A slurry composition comprising:

(a) silica having an aggregate of primary particles, said primary particles having an average diameter of at least seven (7) nanometers, said aggregate having an aggregate size of less than

one (1) micron, and said silica having a hydroxyl content of at least seven (7) hydroxyl groups per nanometer squared;

- (b) a liquid; and
- (c) phytic acid.

61. (New) A slurry for polishing a microelectronic substrate, said slurry comprising precipitated silica having an aggregate of primary particles, said primary particles having an average diameter of at least seven (7) nanometers, wherein said aggregate has an aggregate size of less than one (1) micron, and a hydroxyl content of at least seven (7) hydroxyl groups per nanometer squared,

wherein said slurry provides a removal of at least one material selected from copper, tantalum and silicon dioxide from said microelectronic substrate.

62. (New) The slurry of claim 61 wherein rate of removal of tantalum is equal to or greater than rate of removal of copper.

63. (New) The slurry of Claim 61 wherein said silica has a BET to CTAB ratio of at least 1.2 or greater.